

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	40	V
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Rectified Output Current (See Figure 1)	I _O	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	75	A

Thermal Characteristics

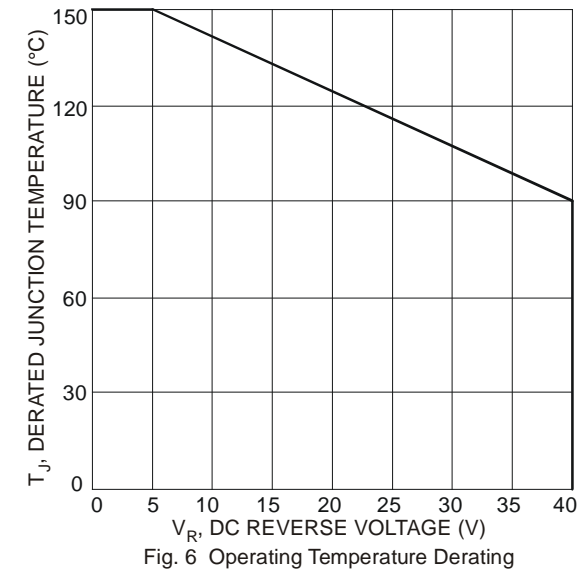
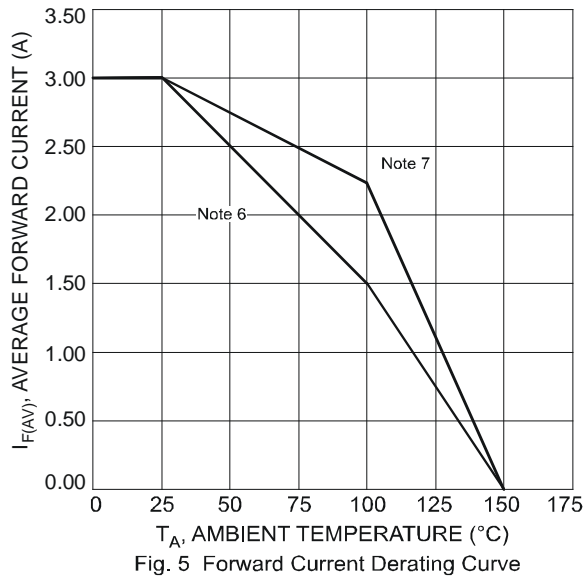
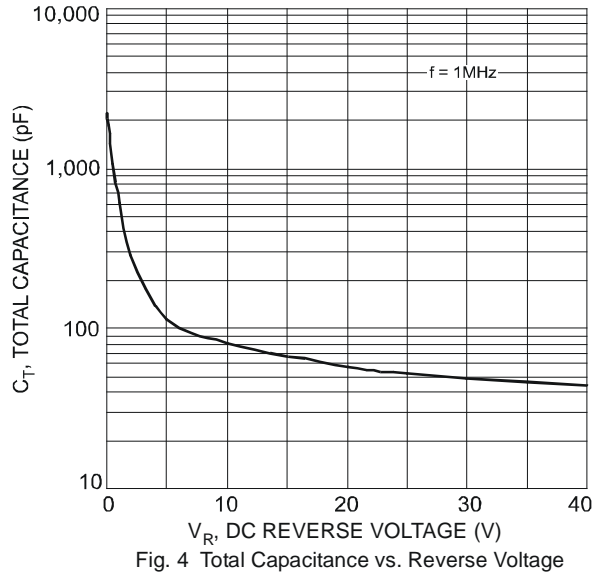
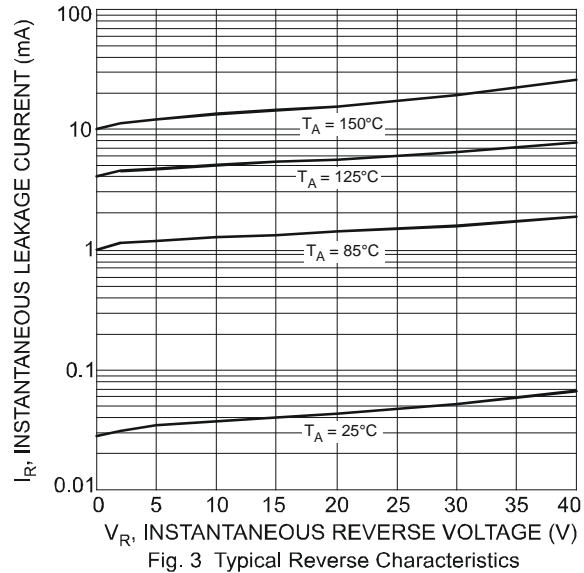
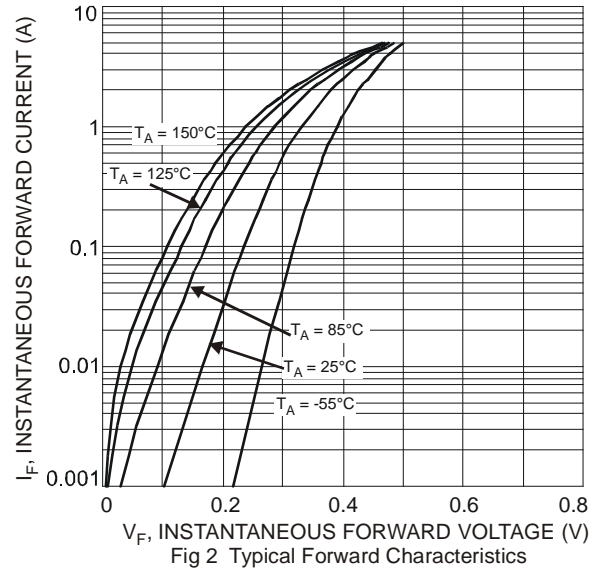
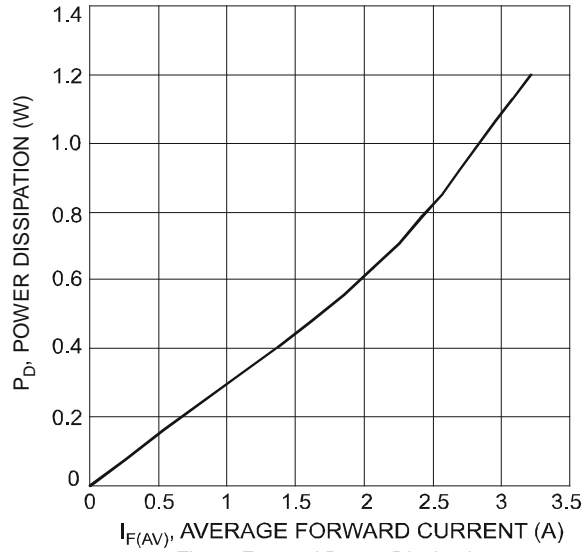
Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	—	—	—
Thermal Resistance Junction to Soldering (Note 5)	R _{θJS}	5	°C/W
Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	175	°C/W
Thermal Resistance Junction to Ambient (Note 7)	R _{θJA}	100	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

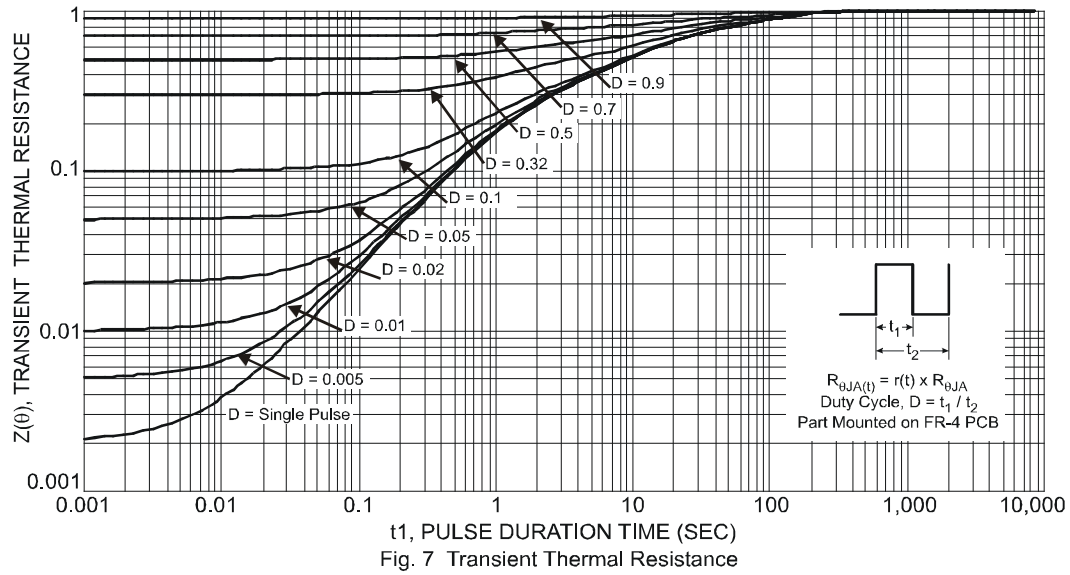
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V _{(BR)R}	40	—	—	V	I _R = 400μA
Forward Voltage Drop	V _F	—	0.30	0.34	V	I _F = 0.5A, T _J = +25°C
		—	0.34	0.39		I _F = 1.0A, T _J = +25°C
		—	0.42	0.47		I _F = 3.0A, T _J = +25°C
Leakage Current (Note 8)	I _R	—	70	400	μA	V _R = 40V, T _J = +25°C
		—	8	40	mA	V _R = 40V, T _J = +125°C

Notes:

5. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
6. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
7. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
8. Short duration pulse test used to minimize self-heating effect.

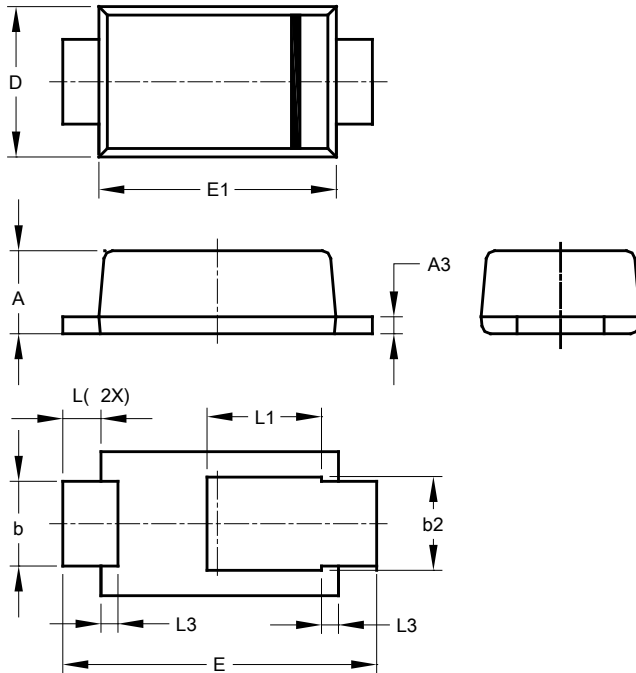




Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123

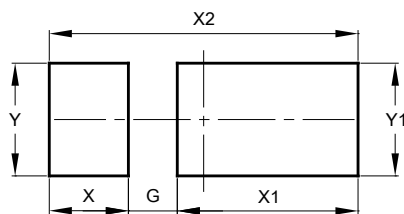


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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